EVERLIGHTAMERICAS

DATASHEET

Top View LED EAPL3527YA2



Features

- P-LCC-2 package.
- · White package.
- · Optical indicator.
- Colorless clear window.
- Wide viewing angle.
- Suitable for vapor-phase reflow, Infrared reflow and wave solder processes.
- Computable with automatic placement equipment.
- Available on tape and reel (8mm Tape).
- Pb-free.
- The product itself will remain within RoHS compliant version.

Descriptions

The EAPL3527YA2 is available in soft orange, green, blue and yellow. Due to the package design, the LED has wide viewing angle and optimized light coupling by inter reflector. This feature makes the SMT TOP LED ideal for light pipe application. The low current requirement makes this device ideal for portable equipment or any other application where power is at a premium.

Applications

- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- Light pipe application.
- General use.



Device Selection Guide

Chip	Emitted Color	Resin Color	
Material	Elintied Color		
AlGaInP	Brilliant Yellow	Water Clear	

Bin Range of Luminous Intensity

Bin	Min	Max	Unit	Condition	
U1	450	565			
U2	565	715	mcd	I _F =20mA	

Bin Range of Dominant Wavelength

Group	Bin Code	Min.	Max.	Unit	Condition
F	DD1	586	588		I _F =20mA
	DD2	588	590		
	DD3	590	592	nm	
	DD4	592	594		

Bin Range of Forward Voltage

Group	Bin	Min.	Max.	Unit	Condition
	0	1.75	1.95	V	I _F =20mA
В	1	1.95	2.15		
	2	2.15	2.35		

Notes:

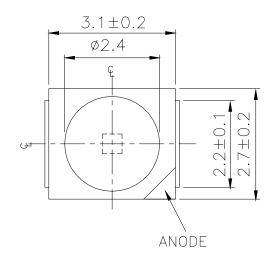
1.Tolerance of Luminous Intensity ±11%

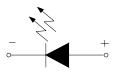
2.Tolerance of Dominant Wavelength ±1nm

3. Tolerance of Forward Voltage ±0.1V

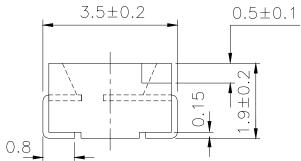


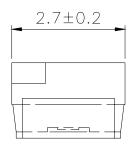
Package Dimensions



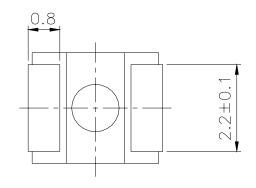


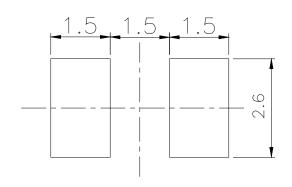
Polarity





For reflow soldering (Proposal)







Absolute Maximum Ratings (Ta=25°C)

Parameter		Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_{F}	50	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	120	mA
Power Dissipation	Pd	100	mW
Electrostatic Discharge(HBM)	ESD	2000	V
Operating Temperature	Topr	-40 ~ +85	$^{\circ}\mathbb{C}$
Storage Temperature	Tstg	-40 ~ +90	$^{\circ}\!\mathbb{C}$
Soldering Temperature	Tsol	Reflow Soldering: 260 °C for 10 sec. Hand Soldering: 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Electro-Optical Characteristics (Ta=25 C)						
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	I_{V}	450		715	mcd	I _F =20mA
Viewing Angle	201/2		120		deg	I _F =20mA
Peak Wavelength	λр		591		nm	I _F =20mA
Dominant Wavelength	λd	586		594	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ		15		nm	I _F =20mA
Forward Voltage	V_{F}	1.75		2.35	V	I _F =20mA
Reverse Current	I_R			10	μΑ	V _R =5V

Notes:

- 1.Tolerance of Luminous Intensity ±11%
- 2.Tolerance of Dominant Wavelength ±1nm
- 3.Tolerance of Forward Voltage ±0.1V



Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed

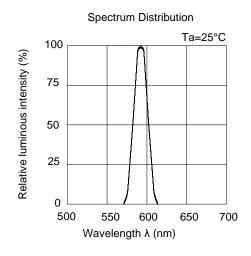
below. Confidence level: 90%

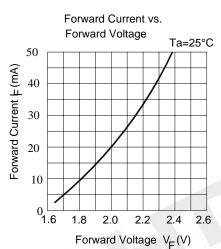
LTPD: 10%

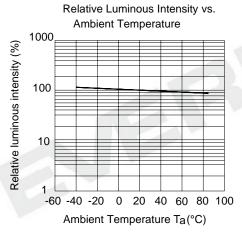
No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C ±5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H:+100°C 15min ∫ 5 min L:-40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H:+100°C 5min ∫ 10 sec L:-10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	$I_F = 20 \text{ mA}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1

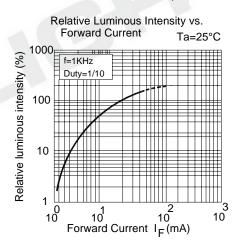


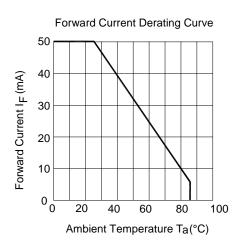
Typical Electro-Optical Characteristics Curves

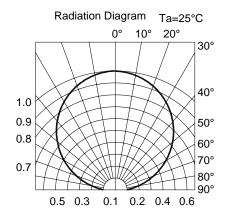








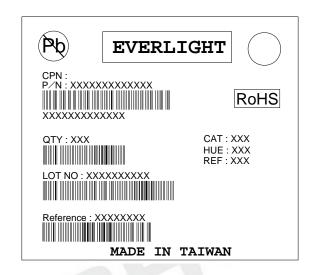




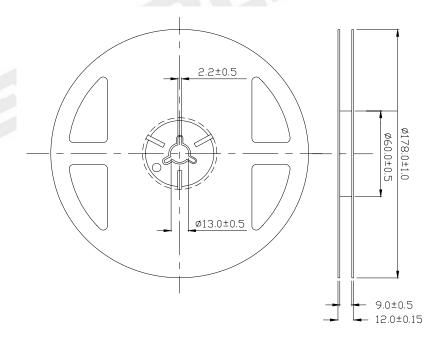


Label Explanation

CAT: Luminous Intensity Rank HUE: Dom. Wavelength Rank REF: Forward Voltage Rank



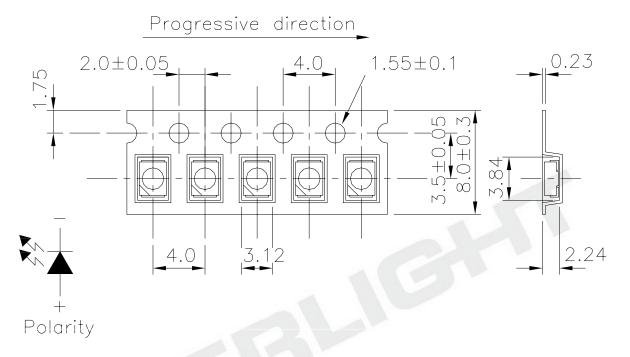
Reel Dimensions



Note: Tolerances Unless Dimension ± 0.1 mm, Unit = mm

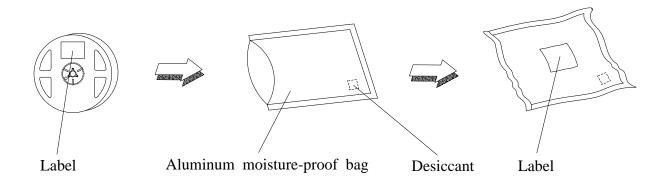


Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel.



Note: Tolerances Unless Dimension ± 0.1 mm ,Unit = mm

Moisture Resistant Packaging





Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

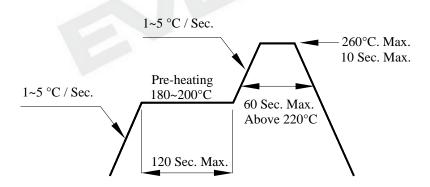
2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30° C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life are 72 hours under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

 Baking treatment: 60±5℃ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.



4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

